



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Application of:)
Bong-Suck KIM et al.) Confirmation No. 4495
Application No.: 10/603,764) Group Art Unit: 3729
Filed: June 26, 2003) Examiner: T. Phan
For: METHOD FOR MANUFACTURING BUILT-UP PRINTED CIRCUIT BOARD WITH STACK TYPE VIA-HOLES (as currently amended)) Mail Stop Amendment)))

Commissioner for Patents
U.S. Patent and Trademark Office
Mail Stop Amendment
Alexandria, VA 22314

Sir:

AMENDMENT

In response to the Office Action dated October 17, 2005, the period for response due January 17, 2006 has been extended one month through February 17, 2006, by the attached petition for extension of time and appropriate fee, please amend the above-identified application as follows.

CONTRACTOR OF PROPERTY OF THE PROPERTY OF T

IN THE TITLE:

Please replace the Title of the Invention with the following amended Title:

METHOD FOR MANUFACTURING BUILT-UP PRINTED CIRCUIT BOARD WITH STACKED STACK TYPE VIA-HOLES AND METHOD FOR MANUFACTURING THE SAME